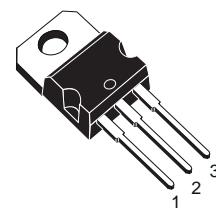


N-CHANNEL 120V - 0.028Ω - 40A TO-220
LOW GATE CHARGE STrixFET™ II POWER MOSFET

TYPE	V _{DSS}	R _{D(on)}	I _D
STP40NF12	120 V	< 0.032 Ω	40 A

- TYPICAL R_{D(on)} = 0.028Ω
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- APPLICATION ORIENTED CHARACTERIZATION



TO-220

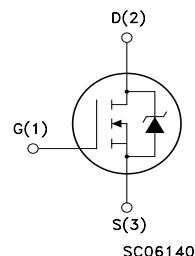
DESCRIPTION

This Power MOSFET series realized with STMicroelectronics unique STrixFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency isolated DC-DC converters for Telecom and Computer application. It is also intended for any application with low gate charge drive requirements.

APPLICATIONS

- HIGH-EFFICIENCY DC-DC CONVERTERS
- UPS AND MOTOR CONTROL

INTERNAL SCHEMATIC DIAGRAM



SC06140

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	120	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	120	V
V _{GS}	Gate- source Voltage	± 20	V
I _D	Drain Current (continuous) at T _C = 25°C	40	A
I _D	Drain Current (continuous) at T _C = 100°C	28	A
I _{DM (●)}	Drain Current (pulsed)	160	A
P _{TOT}	Total Dissipation at T _C = 25°C	150	W
	Derating Factor	1	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	14	V/ns
E _{AS} (2)	Single Pulse Avalanche Energy	150	mJ
T _{stg}	Storage Temperature	– 55 to 175	°C
T _j	Operating Junction Temperature		

(●) Pulse width limited by safe operating area

(1) I_{SD} ≤ 40A, di/dt ≤ 600A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}.

STP40NF12

THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	1	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	°C/W
T _L	Maximum Lead Temperature For Soldering Purpose	300	°C

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V(BR)DSS	Drain-source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0	120			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating, T _C = 125 °C			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20V			±100	nA

ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2	2.8	4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10V, I _D = 20 A		0.028	0.032	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (1)	Forward Transconductance	V _{DS} = 25V, I _D = 20 A		40		S
C _{iss}	Input Capacitance	V _{DS} = 25V, f = 1 MHz, V _{GS} = 0		1880		pF
C _{oss}	Output Capacitance			265		pF
C _{rss}	Reverse Transfer Capacitance			110		pF